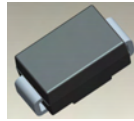


## Features

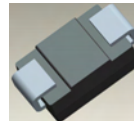
- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

## Mechanical Data

- Case: SMB/SMC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 **(e3)**
- Polarity: Cathode Band or Cathode Notch
- SMB Weight: 0.093 grams (approximate)
- SMC Weight: 0.21 grams (approximate)



Top View



Bottom View

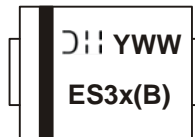
## Ordering Information (Note 3)

Part Number	Case	Packaging
ES3x-13-F	SMC	3000/Tape & Reel
ES3xB-13-F	SMB	3000/Tape & Reel

\* x = Device type, e.g. ES3A-13-F (SMC package); ES3AB-13-F (SMB package).

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
  2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
  3. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



ES3x = Product type marking code, ex: ES3A (SMC package)  
 ES3xB = Product type marking code, ex: ES3AB (SMB package)  
 D11 = Manufacturers' code marking  
 YWW = Date code marking  
 Y = Last digit of year (ex: 2 for 2002)  
 WW = Week code (01 to 53)

### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	ES3A/AB	ES3B/BB	ES3C/CB	ES3D/DB	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>					
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	150	200	V
DC Blocking Voltage (Note 4)	V <sub>R</sub>					
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	105	140	V
Average Rectified Output Current @ T <sub>T</sub> = 100°C	I <sub>O</sub>	3.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	100				A

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	R <sub>θJT</sub>	10	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	50	°C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum Forward Voltage @ I <sub>F</sub> = 3.0A	V <sub>FM</sub>	0.9	V
Peak Reverse Current @ T <sub>A</sub> = 25°C	I <sub>RM</sub>	10	μA
at Rated DC Blocking Voltage (Note 4) @ T <sub>A</sub> = 125°C		500	
Maximum Reverse Recovery Time (Note 6)	t <sub>rr</sub>	25	ns
Typical Total Capacitance (Note 7)	C <sub>T</sub>	45	pF

- Notes:
4. Short duration pulse test used to minimize self-heating effect.
  5. Unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink.
  6. Measured with I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>rr</sub> = 0.25A. See Figure 5.
  7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

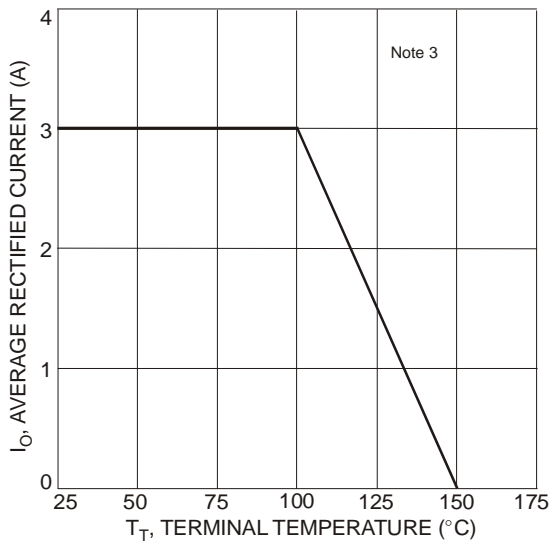


Fig. 1 Forward Current Derating Curve

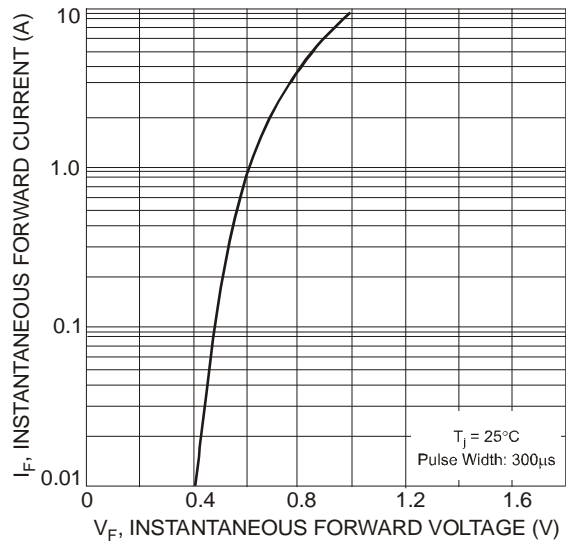


Fig. 2 Typical Forward Characteristics

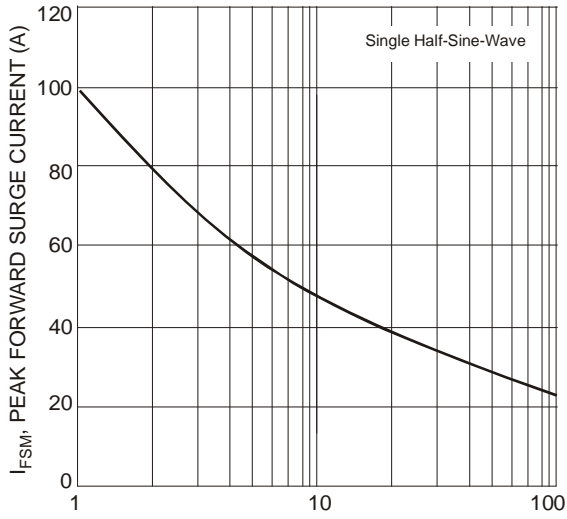


Fig. 3 Surge Current Derating Curve

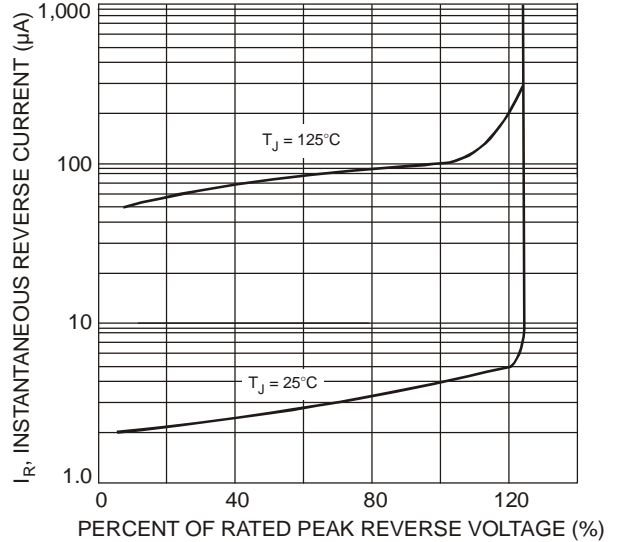
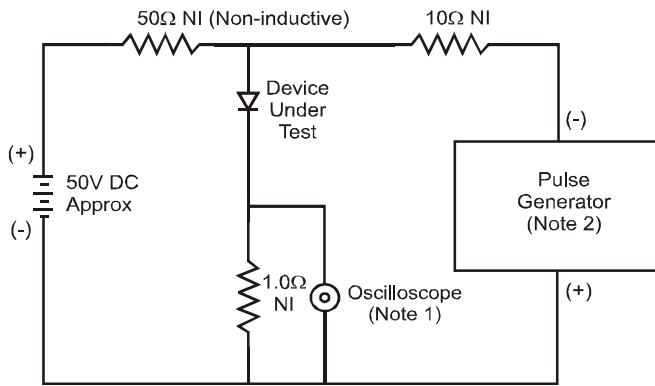
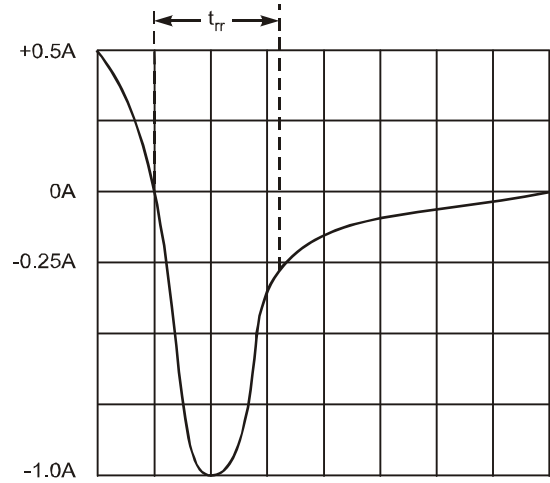


Fig. 4 Typical Reverse Characteristics



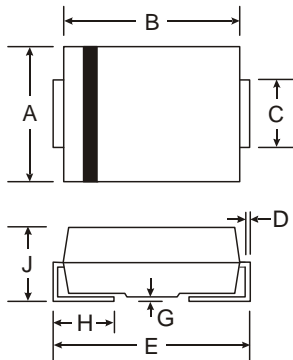
- Notes:
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
  2. Rise Time = 10ns max. Input Impedance = 50Ω.



Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

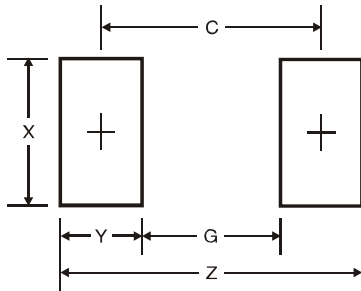
**Package Outline Dimensions**



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

SMC		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

## Suggested Pad Layout



SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

SMC Dimensions	Value (in mm)
Z	9.3
G	4.4
X	3.3
Y	2.5
C	6.8

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